



ALLIANCE MEMORY MDS REPORT

Part Number:		AS4C64M16D3LW-10BCN					
Part Weight:		163.0196 mg					
Item	Part Name	Component wt (mg)	Material Content (Element)	CAS Number	Element wt (%)	Element wt (mg)	wt % of Total unit wt
1	Molding Compound	72.7290	Amorphous silica	60676-86-0	91.80%	66.765222	40.955%
			Epoxy Resin	Trade Secret	2.00%	1.45458	0.892%
			Phenol Resin	Trade Secret	6.00%	4.36374	2.677%
			Carbon Black	1333-86-4	0.20%	0.145458	0.089%
2	Die Attach	3.3460	2-(2-Ethoxyethoxy)ethyl acetate	112-15-2	38.00%	1.27148	0.780%
			Butadiene, acrylonitrile polymer, carboxy-terminated, polymer with bisphenol A and epichlorohydrin	68610-41-3	29.00%	0.97034	0.595%
			Isodecyl alcohol, ethoxylated~	61827-42-7	7.00%	0.23422	0.144%
			Silica Filler	112926-00-8	25.30%	0.846538	0.519%
3	Substrate	43.7300	tert-butyl peroxyneodecanoate	26748-41-4	0.70%	0.023422	0.014%
			Cured Thermosetting Resin	Trade Secret	8.80%	3.84824	2.361%
			Continuous Filament Fiber Glass	65997-17-3	22.00%	9.6206	5.901%
			Copper Foil	7440-50-8	27.00%	11.8071	7.243%
			Morpholine derivarive	Trade Secret	3.60%	1.57428	0.966%
			Talc containing no asbestiform fibers	14807-96-6	3.60%	1.57428	0.966%
			Barium Sulfate	7727-43-7	21.80%	9.53314	5.848%
			Epoxy Resin	Trade Secret	6.90%	3.01737	1.851%
4	Solder Ball	32.6400	Dipropylene glycol monomethyl ether	34590-94-8	6.30%	2.75499	1.690%
			Tin (Sn)	7440-31-5	96.50%	31.4976	19.321%
			Silver (Ag)	7440-22-4	3.00%	0.9792	0.601%
			Copper (Cu)	7440-50-8	0.50%	0.1632	0.100%
5	Bonding Wire	0.2946	Gold (Au)	7440-57-5	99.00%	0.291654	0.179%
			Others	Trade Secret	1.00%	0.002946	0.002%
6	Chip	10.2800	Silicon	7440-21-3	99.00%	10.1772	6.243%
			Others	Trade Secret	1.00%	0.1028	0.063%
Total		163.0196			mg		